

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Stephen E. Greco	07/22/2008
RECEIVING PARTY DATA	
Name:	International Business Machines Corporation
Street Address:	New Orchard Road
City:	Armonk
State/Country:	NEW YORK
Postal Code:	10504
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12183313
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ATTORNEY DOCKET NUMBER:	FIS920080170US1
NAME OF SUBMITTER:	Lisa U. Jaklitsch
Total Attachments: 1 source=FIS920080170US1_final_assignment#page1.tif	

CH \$40.00 12183313

ASSIGNMENT

Whereas, we

**INVENTOR
AND CITY**

(1) **Stephen E. Greco**, City of LaGrangeville, County of Dutchess and State of New York.

have invented certain improvements in

TITLE

VIA DENSITY CHANGE TO IMPROVE WAFER SURFACE PLANARITY

**DATES THAT
INVENTORS
SIGNED THE
DECLARATION**


and executed, respectively, a United States patent application therefor on

(1) 7-22, 2008.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed

(1) 

Stephen E. Greco

on 7-22, 2008